

NJ1800DL Process

Silicon Junction Field-Effect Transistor

- Low-Current
- Low Gate Leakage Current
- High Input Impedance
- Low-Noise

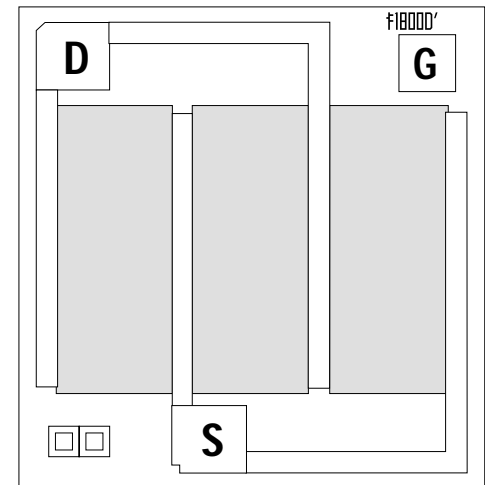
Absolute maximum ratings at 25 °C free-air temperature.

Gate Current, I_G	10 mA
Operating Junction Temperature, T_j	+150°C
Storage Temperature, T_s	- 65°C to +175°C

Device in this Databook based on the NJ1800DL Process.

Datasheet

IF1801



Die Size = 0.052" X 0.052"

All Bond Pads \geq 0.004" Sq.

Substrate is also Gate.

At 25°C free air temperature:

Static Electrical Characteristics

		NJ1800DL Process						
		Min	Typ	Max	Unit	Test Conditions		
Gate Source Breakdown Voltage	$V_{(BR)GSS}$	- 15	- 25		V	$I_G = - 1 \mu A, V_{DS} = 0V$		
Reverse Gate Leakage Current	I_{GSS}		- 30	- 100	pA	$V_{GS} = - 10V, V_{DS} = 0V$		
Drain Saturation Current (Pulsed)	I_{DSS}	50		800	mA	$V_{DS} = 10V, V_{GS} = 0V$		
Gate Source Cutoff Voltage	$V_{GS(OFF)}$	- 0.1		- 4	V	$V_{DS} = 10V, I_D = 1 nA$		

Dynamic Electrical Characteristics

Forward Transconductance (Pulsed)	g_{fs}		350		mS	$V_{DS} = 10V, V_{GS} = 0V$	$f = 1 kHz$
Input Capacitance	C_{iss}		160		pF	$I_D = 1 mA, V_{GS} = 0V$	$f = 1 MHz$
Feedback Capacitance	C_{rss}		50		pF	$V_{DS} = 10V, V_{GS} = 0V$	$f = 1 MHz$
Equivalent Noise Voltage	\hat{e}_N		0.7		nV/ \sqrt{HZ}	$V_{DG} = 4V, I_D = 5 mA$	$f = 1 kHz$

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